

IN THE CLAIMS

1. (Previously presented) An assembly for providing solderless electrical connection between first and second substrates aligned in a stacked configuration, said assembly comprising:

a conductor assembly having at least one elongate conductor adapted to engage a first electrical contact on said first substrate on one end and a second electrical contact on said second substrate on a second end thereof, said conductor having a three-bend hook shape at both the first and second ends thereof to provide a spring force on both the first and second ends thereof and

means for retaining said conductor in abutting contact with said first and second contacts and thereby effect a solderless electrical connection between said first contact on said first substrate and said second contact on said second substrate.

2. Canceled

3. Canceled

4. (Previously presented) The assembly of Claim 1 wherein said conductor is constrained by a dielectric between the ends thereof.

5. (Previously presented) The assembly of Claim 4 wherein said conductor assembly includes a plurality of conductors.

6. (Previously presented) The assembly of Claim 5 wherein said conductor assembly is retained within an elongate housing.

7. (Previously presented) The assembly of Claim 6 wherein said housing is retained within a frame.

8. (Previously presented) The assembly of Claim 7 wherein said housing is retained within said frame by at least one pin at each end thereof.

9. (Previously presented) assembly of Claim 8 wherein said pin is retained by said frame.

10. (Previously presented) A high density electrical assembly adapted to make solderless electrical contacts between plural circuit boards aligned in a stacked configuration, said assembly comprising:

a conductor assembly having plural elongate conductors adapted to engage a first electrical contact on a first circuit board on one end and a second electrical contact on a second circuit board on a second end thereof, each conductor having a three-bend hook shape at both the first and second ends thereof to provide a spring force on both the first and second ends thereof and constrained by a dielectric between the ends thereof and

means for retaining each conductor in abutting contact with said first and second contacts and thereby effect a solderless electrical connection between said first contact on said first substrate and said second contact on said second substrate.

11. (Canceled)